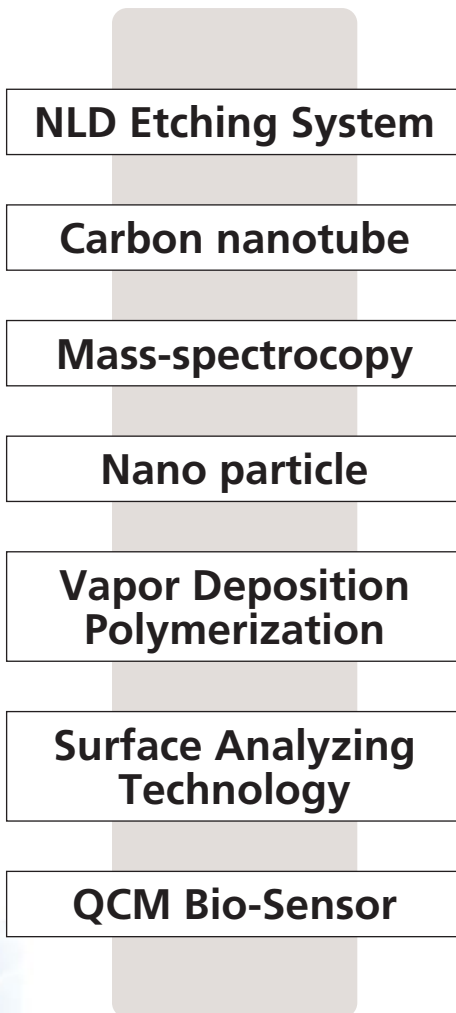


■ ULVAC original technologies for MEMS device production



● Processing Technology for MEMS Production

Etching Processing

Making material and etching them.
 Example: **Photo etching**, **Anisotropic etching**, Micro PDM
 Micro-beam processing, Machining.

Deposition Processing

Forming materials and simultaneously shaping and producing functional device.
 Example: **Sputtering**, **Evaporation**, **CVD**, **Oxidation**,
 Light molding.

Combined Processing

Matching which combine etching processry and deposition processing.
 - Processing minute parts and assembling them simultaneously -
 Example: Micro ECM, Surface layer etching,
 Cylindrical geometry stator manufacturing,
 Shell body manufacturing.

Dry Etching System **NLD-6000**

For Deep Trench Etching of SiO₂

Features

- NLD plasma source equipped. (NLD = Neutral Loop Discharge)
- High rate etching. (0.6 ~ 0.7 μm/min SiO₂)
- Ideal anisotropic etching performance using low pressure and high density plasma.
- High etching uniformity (1%) for optical parts manufacturing.

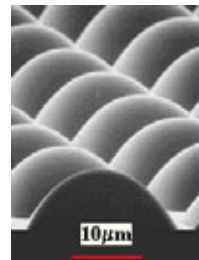
* NLD-500 available to R&D



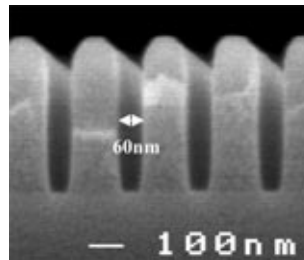
Example: Post etching profile



Optical device



Micro-lens



Organic Low-k

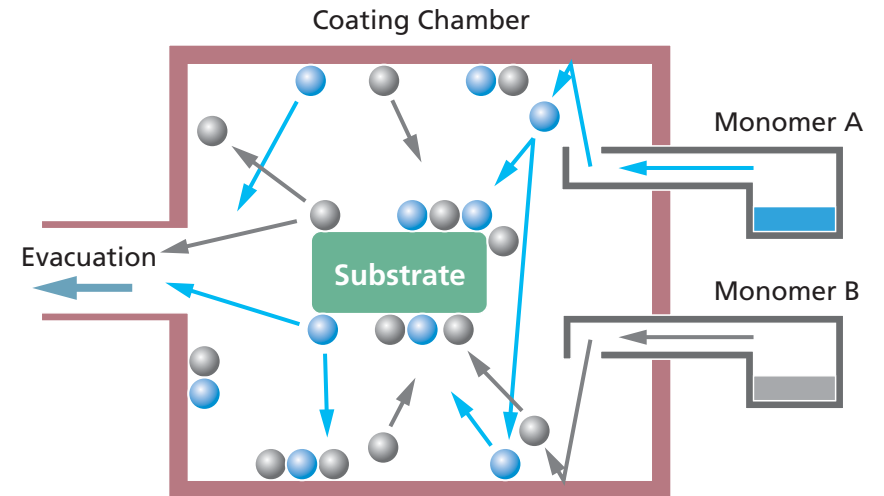
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ULVAC original technology **Vapor Deposition Polymerization**

For polymer thin film production

In the Vapor Deposition Polymerization (VDP) process the diamine and the dianhydride are coevaporated onto a substrate where they react to form a polyimide precursor, which converts to polyimide upon thermal curing.

Outline of VDP



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